

**On-State Current** 

**Gate Trigger Current** 

25 Amp

2mA to 25mA 2mA to 40mA

**Off-State Voltage** 

400 V ÷ 800 V

#### **FEATURES**

- Glass/passivated die junctions
- High current SCR
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

# (e3)

RoHS

#### **MECHANICAL DATA**

- Case: (D2PAK) / (TO-220F) & (TO-220AB). Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

#### **TYPICAL APPLICATIONS**

The **standard** gate SCR FS2510 and FS2514 series is suitable for a wide range of applications, e.g., Overvoltage Crowbar protection, Motor Control circuits in Power Tools and domestic appliances, inrush current limiting circuits, capacitive discharge ignition and voltage regulation circuits.

### Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I <sub>T(RMS)</sub>	On-state Current	180 ° Conduction Angle, T <sub>c</sub> = 110 °C	25	А
I <sub>T(AV)</sub>	Average On-state Current	Half Cycle, $\Theta$ = 180 °, T <sub>c</sub> = 110 °C	16	А
I <sub>TSM</sub>	Non-repetitive On-State Current	Half Cycle, 60 Hz	330	А
I <sub>TSM</sub>	Non-repetitive On-State Current	Half Cycle, 50 Hz	300	А
l <sup>2</sup> t	Fusing Current	t <sub>p</sub> = 10ms, Half Cycle	450	A <sup>2</sup> s
I <sub>GM</sub>	Peak Gate Current	20 µs max.	4	А
P <sub>GM</sub>	Peak Gate Dissipation	20 µs max.	20	W
P <sub>G(AV)</sub>	Gate Dissipation	20 ms max.	1	W
T <sub>j</sub>	Operating Temperature		(-40 to + 125)	°C
T <sub>stg</sub>	Storage Temperature		(-40 to + 150)	°C
T <sub>sld</sub>	Soldering Temperature	10 ms max.	260	°C
$V_{RGM}$	Reverse Gate Voltage		5	V
V <sub>iso</sub>	R.M.S. isolation voltage 50/60 Hz sinusoidal waveform		2.500	Vac

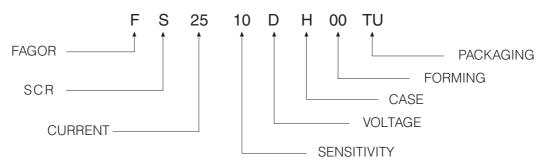
SYMBOL	PARAMETER	VOLTAGE			Unit	
	OTIVIDOL	17 W WILL LIV	D	М	N	
	$V_{DRM}/V_{RRM}$	Repetitive Peak Off State Voltage	400	600	800	V



#### Electrical Characteristics at Tamb = 25 °C

SYMBOL	PARAMETER	CONDITIONS		SENSITIVITY		Unit	
01202					10 14		
I <sub>GT</sub>	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33\Omega.$		MIN MAX	2 25	4 40	m A
$V_{GT}$	Gate Trigger Voltage	$V_D = 12 V_{DC}$ , $R_L = 33 \Omega$ .		MAX	1.	.3	V
$V_{GD}$	Gate Non Trigger Voltage	$\begin{aligned} V_D &= V_{DRM} , R_L = 3.3 k \Omega, \\ T_j &= 125 ^{\circ} C \end{aligned}$		MIN	0	.2	V
I <sub>H</sub>	Holding Current	$I_T = 500 \text{ mA},$		MAX	40	50	m A
IL	Latching Current	$I_{G} = 1.2 I_{GT}$		MAX	60	90	m A
dV / dt	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$ , Gate of $T_j = 125  ^{\circ}C$	open	MIN	500	1500	V/µs
dl / dt	Critical Rate of Current Rise	$T_j = 125 ^{\circ}\text{C}$	f = 60 Hz, PAK/TO-220AB D-220F	MIN MIN	5( 10		A/µs
$V_{TM}$	On-state Voltage	at $I_T = 50$ Amp, $tp = 380 \mu s$	s, T <sub>j</sub> = 25 °C	MAX	1.	6	V
V <sub>t 0</sub>	Threshold Voltage	T <sub>j</sub> = 125 °C		MAX	0.7	77	V
r <sub>d</sub>	Dynamic resistance	T <sub>j</sub> = 125 °C		MAX	1	4	mΩ
I <sub>DRM</sub> / I <sub>RRM</sub>		$ \begin{aligned} V_D &= V_{DRM} , \\ V_R &= V_{RRM} , \end{aligned} $	$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$	MAX MAX	2		mΑ μΑ
$R_{\text{th(j-c)}}$	Thermal Resistance Junction-Case for DC	for AC 360 ° conduction D2 angle TO	PAK/TO-220AB )-220F		1	ļ	°C/W
R <sub>th(j-a)</sub>	Thermal Resistance Junction-Amb for DC	-	D2PAK TO-220F TO-220AB		4: 5 6	5	°C/W

#### **Part Number Information**





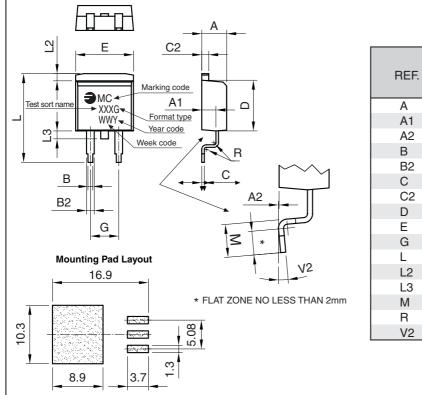
# **Ordering information**

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FS2510DG 00TR	TR	13" diameter tape and reel	800	1.50

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FS2510DH 00TU	TU	TUBE	1000	2.30

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FS2510DW 00TU	TU	TUBE	1000	2.00

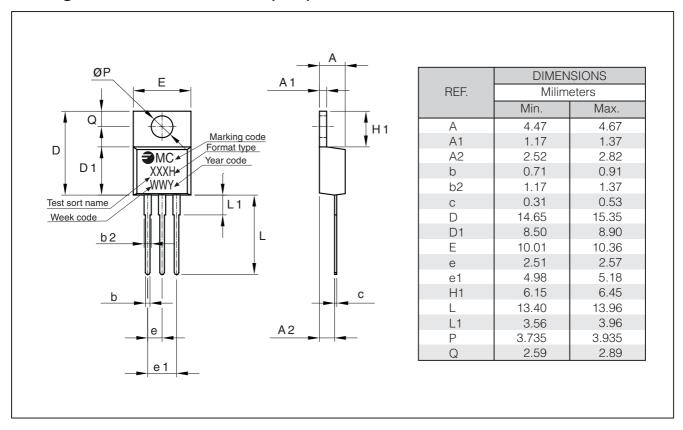
# Package Outline Dimensions: (mm) TO-263AB (D2PAK)



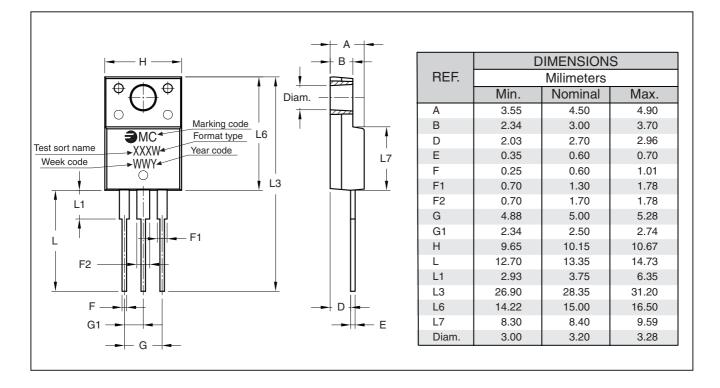
	DIMENSIONS				
REF.	Milimeters				
	Min.	Nominal	Max.		
Α	4.40	4.45	4.60		
A1	2.49	2.50	2.69		
A2	0.03	0.10	0.23		
В	0.70	0.90	0.93		
B2	1.14	1.03	1.70		
С	0.45	0.45	0.60		
C2	1.23	1.23	1.36		
D	8.95	9.00	9.35		
E	10.00	10.25	10.40		
G	4.88	5.15	5.28		
L	15.00	15.40	15.85		
L2	1.27	1.27	1.40		
L3	1.40	1.55	1.75		
М	2.40	3.00	3.20		
R	0.40 typ				
V2	0°		8°		



# Package Outline Dimensions: (mm) TO-220AB



# Package Outline Dimensions: (mm) TO-220F



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# Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum average power dissipation versus average on-state current.

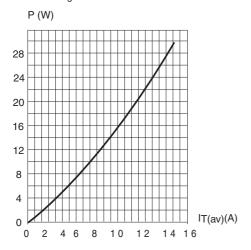


Fig. 3: Relative variation of thermal impedance junction to case versus pulse duration.

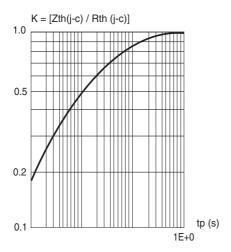


Fig. 5: Non repetitive surge peak on-state current versus number of cycles.

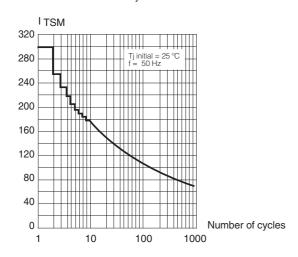


Fig. 2: Average and D.C. on-state current versus case temperature.

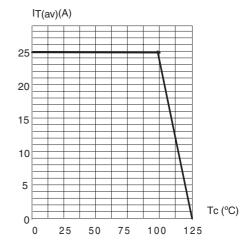


Fig. 4: Relative variation of gate trigger current, holding and latching current versus junction temperature.

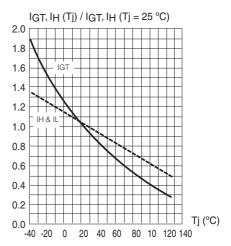


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I<sup>2</sup>t.

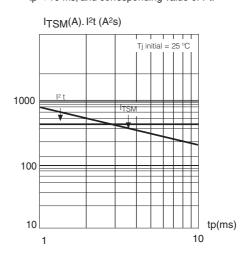




Fig. 7: On-state characteristics (maximum values).

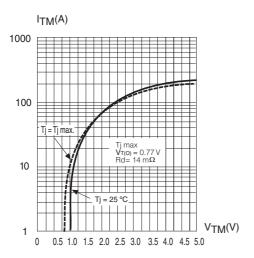


Fig. 8: D<sup>2</sup>PAK RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35µm), full cycle.

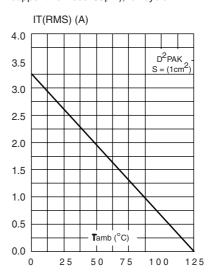
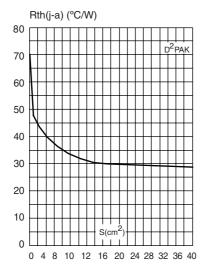


Fig. 9: D<sup>2</sup>PAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FRA, copper thickness: 35µm).





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